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APPLICATION DATA SHEET

Applicant Information

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Citizenship Country:: Japan

Correspondence Information

Correspondence Customer Number:: 06449

Application Information

Title Line One:: ELECTRODEPOSITED COPPER FOIL WITH CARRIER
Title Line Two:: FOIL ON WHICH A RESIN LAYER FOR FORMING
Title Line Three:: INSULATING LAYER IS FORMED, COPPER-CLAD
Title Line Four:: LAMINATE, PRINTED WIRING BOARD, METHOD FOR
Title Line Five:: MANUFACTURING MULTILAYER COPPER-CLAD
Title Line Six:: LAMINATE, AND METHOD FOR MANUFACTURING
Title Line Seven:: PRINTED WIRING BOARD
Total Drawing Sheets:: 13
Formal Drawings?:: New
Application Type:: Utility
Docket Number:: 3209-124

Secrecy Order in Parent Appl?:: No

Representative Information

Representative Customer Number:: The practitioners associated
Representative Customer Number:: with customer number 06449

Domestic Priority Information

This application is a:: 371 of

>Application One:: PCT/JP2005/004501
Filing Date:: March 15, 2005
Patent Number::

Foreign Priority Information

Foreign Application One:: JP2004-075235
Filing Date:: March 16, 2004
Country:: Japan
Priority Claimed:: Yes

Assignment Information

Assignee name:: Mitsui Mining & Smelting Co., Ltd.
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